

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-11. (Canceled)
12. (Currently amended) A semiconductor device ~~that is manufactured by the method according to claim 1~~ comprising:

a substrate having an electrode formed thereon;

a cover affixed to the substrate, the cover having a first opening with an adhesive disposed therein for affixing the cover to the substrate, and a second opening that receives and surrounds the electrode when the cover is affixed to the substrate, the first opening configured so that adhesive is present only in the first opening and not in the second opening.

13. (Original) The semiconductor device according to claim 12, further comprising a support member attached to the semiconductor device.

14. (Original) The semiconductor device according to claim 12, further comprising:

a circuit substrate that is electrically coupled to the electrode of the semiconductor device.

15. (Original) An electronic equipment comprising:
the semiconductor device according to claim 12.

16. (Currently amended) A cover for a semiconductor device having a substrate with an optical unit formed thereon, the cover comprising:

a portion defining a first opening on a surface of the cover;

a portion defining a second opening on the surface of the cover; and

a translucent portion in at least the portion defining the second opening, wherein the first opening is formed along a circumference of the second opening, and wherein the first opening contains an adhesive for affixing the cover to the substrate, and wherein the second opening is formed so as to include an receive and

surround the optical unit inside of the second opening when the cover is affixed to the substrate, and wherein the ~~optical unit of the semiconductor substrate~~ second opening that includes the optical unit is sealed from the adhesive in the first opening.

17. (Currently amended) The cover for a the semiconductor device according to claim 16, wherein the first opening is formed so as to surround the second opening.

18. (Currently amended) The cover for a the semiconductor device according to claim 16, further comprising:

a portion defining a third opening on the surface that includes the portion defining the first opening and the portion defining the second opening and wherein the third opening is formed along a circumference of the second opening.

19. (Currently amended) The cover for a the semiconductor device according to claim 16, wherein the first opening is formed between the second opening and the third opening.

20. (Currently amended) The cover for a the semiconductor device according to claim 16, further comprising a portion defining a through-hole that extends from a back side of the surface that includes the portion defining the first opening to inside the first opening.

21. (Currently amended) The cover for a the semiconductor device according to claim 20, further comprising:

a portion that is formed in line along the cover; and
a slit that is formed in line on the portion of the first opening that is formed in line.

22. (Currently amended) The cover for a the semiconductor device according to claim 16, wherein the first opening is formed so as to penetrate from one side of the cover to the other side of the cover.

23. (Currently amended) A cover for a semiconductor device, comprising:
a portion defining a first opening on a surface of the cover;

a portion defining a second opening on the surface of the cover; and
a translucent portion in at least the portion defining the second opening,
wherein the first opening is formed along a circumference of the second opening and
receives an adhesive for affixing the cover to the substrate, the adhesive being
sealed within the first opening and not present in the second opening, and the
second opening is formed ~~so as~~ to include ~~the~~ an optical unit inside of the second
opening.